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PATENT NUMBER

U.S. **UTILITY** Patent Application

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PATENT DATE

APPLICATION NO. CONT/PRIOR CLASS SUBCLASS ART UNIT EXAMINER 09/855820 2811 , Ruben Madrid Carrier with metal bumps for semiconductor die packages

ISSUING CLASSIFICATION												
ORIGINAL					CROSS REFERENCE(S)							
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TERMINAL		DRAWINGS	,	CLAIMS ALLOWED		
L DISCLAIMER	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
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subsequent to (date) has been disclaimed.	(Assistant Examiner) (Date)					
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not extend beyond the expiration date of U.S Patent. No				ISSUE FEE		
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